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What is claimed is:

1. A back electrode type electronic part comprising:
 - a main body including a circuit; and
 - electrodes arranged for solder bumps on a back surface portion of said electronic part and connected to said circuit, and
 - wherein each of groups of said electrodes at portions of the electrode arrangement is provided for a single first solder bump which is larger than second solder bumps for said electrodes arranged other than said corner portions, and
 - wherein said group of electrodes includes electrodes having a substantially same potential level when said circuit operates.
2. A back electrode type electronic part according to claim 1, wherein said electrodes are arranged in a matrix, and said portions are 4 corner portions.
3. A back electrode type electronic part according to claim 1, wherein said group of electrodes includes a non-contact electrode which is not connected to said circuit.
4. A back electrode type electronic part according to claim 1, wherein one of said electrodes of said

group is a signal electrode.

5. A back electrode type electronic part according to claim 1, wherein one of said electrodes of said group is a ground potential electrode.

6. A back electrode type electronic part according to claim 1, wherein one of said electrodes of said group is a power supply potential electrode.

7. An electronic assembly comprising:

a back electrode type electronic part comprising:

5 a main body including a circuit, and
electrodes provided on a back surface
portion of said electronic part and connected to said
circuit, wherein groups of said electrodes at portions
of the electrode arrangement is groups of integrated
electrodes, and wherein said group of integrated
10 electrodes includes said electrodes having a
substantially same potential level when said circuit
operates;

a printed circuit board having substrate
electrodes corresponding to said electrodes provided
15 for said electronic part, wherein one of said
substrate electrodes as a first substrate electrode is
provided for each of said groups of integrated

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electrodes, and said substrate electrodes as second substrate electrodes other than said first substrate
20 electrodes are provided for said electrodes of said electronic part other than said integrated electrodes; and

solder bumps including first solder bumps connected with said groups of integrated electrodes
25 and said first substrate electrodes and second solder bumps connected with said second substrate electrodes and said electrodes of said electronic part other than said integrated electrodes.

8. A back electrode type electronic part according to claim 7, wherein said electrodes of said electronic part are arranged in a matrix, and said portions are 4 corner portions.

9. A back electrode type electronic part according to claim 7, wherein one of said integrated electrodes of said group is a non-contact electrode which is not connected to said circuit.

10. A back electrode type electronic part according to claim 7, wherein one of said integrated electrodes of said group is a signal electrode.

11. A back electrode type electronic part according

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to claim 7, wherein one of said electrodes of said group is a ground potential electrode.

12. A back electrode type electronic part according to claim 7, wherein one of said electrodes of said group is a power supply potential electrode.